FutureCom™ Cat. 3 / ISDN Patch Panel 19”, 1U, 50 Ports

High-grade steel

The FutureCom™ Cat.3 / ISDN telephone patch panel offers a simple and economical way to connect the telephone system or the telephone backbone with the structured wiring.
The telephone connection can be made by one or two pairs (analogue and ISDN technology)



Part Number: CAXCSV-05000-C001

Features

- 19” patch panel, 1U with 50 unshielded 8-pin RJ45 jacks
- Wire connection via 4-pin LSA/110 connect dual cutting clamps for AWG 22-26
- Wiring according to ISO/IEC 11801/EN 50173-1, configuration: Pin 3/6 and Pin 4/5
- Grounding via M6 screw with nut and lock washer in the patch panel
- Shield connection directly on the circuit board
- Integrated cable strain relief

Specifications

General Specifications	
Category	3
Dust Protection	No

Temperature Range	
Installation and Assembly	-40 °C to 70 °C
Operation	-10 °C to 60 °C

Design - Hardware	
Number of Ports	50
Height Unit	1U
Colour	high-grade steel
Housing Material	High-grade steel

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CORNING

Mechanical Characteristics	
Dimensions (L x W x H)	483 mm to 44 mm to 120 mm

Chemical characteristics	
Environmental Compatibility	Recyclable
RoHS	Free of hazardous substances according to RoHS 2002/95/EG

Ordering Information

Part Number	CAXCSV-05000-C001
Product Description	FutureCom Cat. 3 / ISDN Telephone Patch Panel, unshielded, 50x RJ45, configuration 4.5 and 3.6, LSA-PLUS, 1U
EAN Code	4042673102380
Colour	high-grade steel
Height Unit	1U
Weight	1.166 kg

Shipping Information

Units per Delivery	1/1

RoHS COMPLIANT

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